



Product Change Notification

Change Notification #: 117431 - 00
Change Title: Hot Swap Backplane Improvement
F2U8X25S3PHS,
PCN 117431-00, Product Design,
Capacitor cut out
Date of Publication: February 20, 2020

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	March 3, 2020
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is cutting out the capacitor C3N4 from all products listed in below "Product Affected" table. To improve voltage regulation sense feedback loop. Because of this change TA number and PBA will roll-up.

Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
F2U8X25S3PHS	955870	H97230-004	H88386-251	H97230-005	H88386-252

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 20, 2020	00	Originally Published PCN



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117431 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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